APT30D120SG Datasheet Ultrafast Soft Recovery Rectifier Diode

March 2018





Contents

1	Revis	Revision History			
	1.1	Revision A	. 1		
2		uct Overview			
	2.1	Features	. 2		
	2.2	Benefits	. 2		
	2.3	Applications	. 2		
2	Пось	wice Considerations	2		
3	Elect	rical Specifications	. პ		
		Absolute Maximum Ratings			
	3.2	Typical Electrical Performance	. 3		
	3.3	Typical Performance Curves	. 5		
	3.4	Reverse Recovery Overview	. 8		
1	Pack	age Specification	q		
7					
	4.1	Package Outline Drawing	. 9		



1 Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

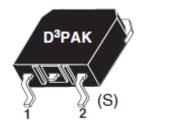
1.1 Revision A

Revision A was published in March 2018. It is the first publication of this document.



2 Product Overview

This section outlines the product overview for the APT30D120SG device.





Back of Case - Cathode

2.1 Features

The following are key features of the APT30D120SG device:

- Ultrafast recovery times
- Soft recovery characteristics
- Low forward voltage
- Low leakage current
- RoHS compliant

2.2 Benefits

The following are benefits of the APT30D120SG device:

- Low switching losses
- Low noise (EMI) switching
- Cooler operation
- Higher reliability systems
- Increased system power density

2.3 Applications

The APT30D120SG device is designed for the following applications:

- Power factor correction (PFC)
- Anti-parallel diode
 - Switchmode power supply
 - Inverters
- Freewheeling diode
 - Motor controllers
 - Converters
 - Inverters
- Snubber diode



3 Electrical Specifications

This section details the electrical specifications for the APT30D120SG device.

3.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings for the APT30D120SG device.

All Ratings: $T_c = 25$ °C unless otherwise specified.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
VR	Maximum DC reverse voltage	1200	V
VRRM	Maximum peak repetitive reverse voltage	1200	
V _{RWM}	Maximum working peak reverse voltage	1200	
I _{F(AV)}	Maximum average forward current (TC= 128 °C, duty cycle = 0.5)	30	Α
I _F (RMS)	RMS forward current	59	_
İfsm	Non-repetitive forward surge current (T _J = 45 °C, 8.3 ms)	210	_
Тл, Тятб	Operating and storage temperature range	-55 to	°C
		175	
Tι	Lead temperature for 10 s	300	=

3.2 Typical Electrical Performance

The following table shows the static electrical characteristics of the APT30D120SG device.

Table 2 • Static Electrical Characteristics

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	Unit
.,	Forward voltage	I _F = 30 A		2.0	2.5	- V
VF		I _F = 60 A		2.3		
		I _F = 30 A, T _J = 125 °C		1.8		_
Irm	Maximum reverse leakage current	$V_R = V_R$ rated			250	μΑ
		V _R = V _R rated, T _J = 125 °C			500	=
Ст	Junction capacitance	V _R = 200 V		32		pF



The following table shows the dynamic characteristics of the APT30D120SG device.

Table 3 • Dynamic Characteristics

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	Unit
trr	Reverse recovery time	$I_F = 1 \text{ A}$ $di_F/dt = -100 \text{ A}/\mu\text{s}$ $V_R = 30 \text{ V}$ $T_J = 25 \text{ °C}$		31		ns
trr	Reverse recovery time	I _F = 30 A		370		-
Qrr	Reverse recovery charge	_ di _F /dt = -200 A/μs _ V _R = 800 V		660		nC
IRRM	Maximum reverse recovery current	Tc = 25 °C		5		Α
trr	Reverse recovery time	I _F = 30 A		500		ns
Qrr	Reverse recovery charge	- di _F /dt = -200 A/μs - V _R = 800 V		3450		nC
Irrm	Maximum reverse recovery current	VR = 800 V Tc = 125 °C		12		Α
trr	Reverse recovery time	I _F = 30 A		220		ns
Qrr	Reverse recovery charge	di _F /dt = −1000 A/μs V _R = 800 V		4650		nC
IRRM	Maximum reverse recovery current	Tc = 125 °C		37		Α

The following table shows the thermal and mechanical characteristics of the APT30D120SG device.

Table 4 • Thermal and Mechanical Characteristics

Symbol	Characteristic/Test Conditions	MIN	TYP	MAX	Unit
Reuc	Junction-to-case thermal resistance			0.61	- °C/W
Reja	Junction-to-ambient thermal resistance			40	- C/ VV
WT	Package weight		0.14		OZ
			4.0		g



3.3 Typical Performance Curves

This section shows the typical performance curves for the APT30D120SG device.

Figure 1 • Maximum Effective Thermal Impedance, Junction-to-Case vs. Pulse Duration

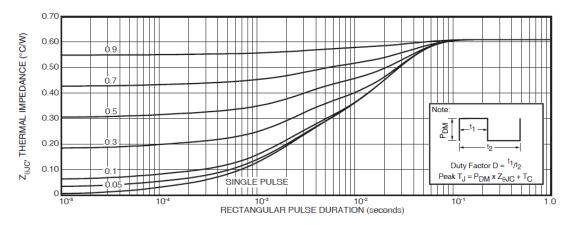


Figure 2 • Transient Thermal Impedance Model

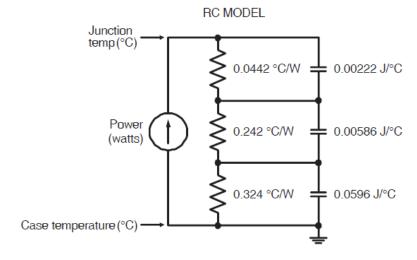




Figure 3 • Forward Current vs. Forward Voltage

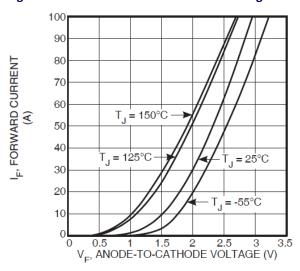


Figure 5 • Qrr vs. Current Rate of Change

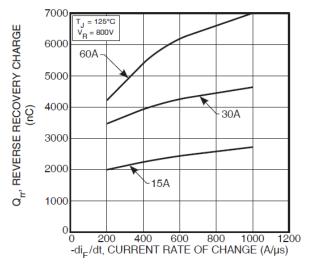


Figure 7 • Dynamic Parameters vs. Junc Temp

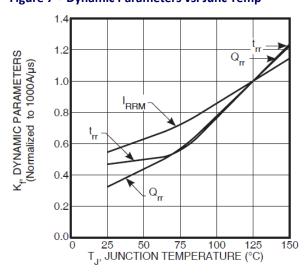


Figure 4 • trr vs. Current Rate of Change

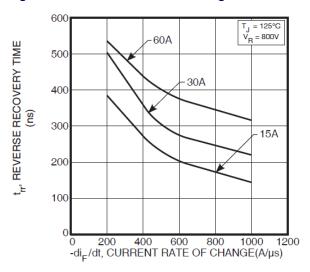


Figure 6 • Irrm vs. Current Rate of Change

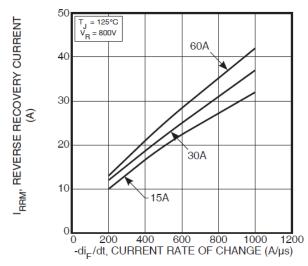


Figure 8 • Max Avg Forward Current vs. Case Temp

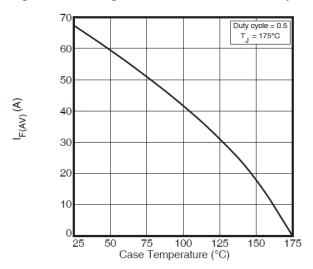
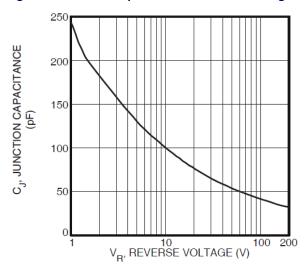




Figure 9 • Junction Capacitance vs. Reverse Voltage





3.4 Reverse Recovery Overview

The following illustration shows the reverse recovery testing and measurement information for the APT30D120SG device.

Figure 10 • Diode Test Circuit

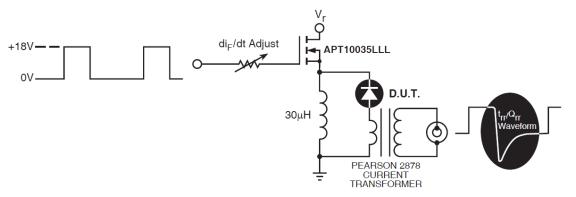
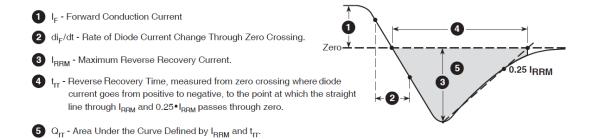


Figure 11 • Diode Reverse Recovery Waveform and Defintions





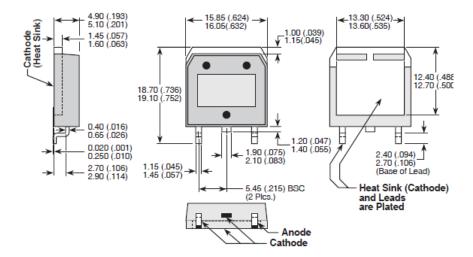
4 Package Specification

This section outlines the package specification for the APT30D120SG device.

4.1 Package Outline Drawing

This section details the D3PAK package drawing of the APT30D120SG device. Dimensions are in millimeters and (inches).

Figure 12 • Package Outline Drawing







Microsemi Corporate Headquarters

One Enterprise, Aliso Viejo, CA 92656 USA Within the USA: +1 (800) 713-4113 Outside the USA: +1 (949) 380-6100 Fax: +1 (949) 215-4996 Email: sales.support@microsemi.com www.microsemi.com

© 2018 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are trademarks of Microsemi Corporation. All other trademarks and service marks are the property of their respective owners

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or prameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided is, where is' and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without notice.

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, California, and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

050-5946

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Rectifiers category:

Click to view products by Microchip manufacturer:

Other Similar products are found below:

FERD15S50SB-TR D91A DA24F4100L DD89N1600K-A DD89N16K-K RL252-TP DLA11C-TR-E DSA17G JANTX1N4148UB

JANTX1N5634A 1N4005-TR BAV199-TP UES1306HR2 UF4003-TP UFS120Je3/TR13 JANS1N6640US DD89N16K DD89N16K-A

481235F DSP10G-TR-E RRE02VS6SGTR 067907F MS306 ND104N08K SPA2003-B-D-A01 VS-80-6193 VS-66-9903 VGF0136AB

US2JFL-TP UFS105Je3/TR13 A1N5404G-G ACGRA4007-HF ACGRB207-HF RF301B2STL RF501B2STL 1SS355 RR UES1306

UES1302 BAV199E6433HTMA1 ACGRC307-HF ACEFC304-HF DZ-1380 JANTXV1N5637A JANTX1N5555 JANTXV1N5660A

JAN1N5555 JANTX1N5822US MUH1PCHM389A UES1106 GS2K-LTP